Fusabond® M623XF

DuPont Packaging & Industrial Polymers - Polyethylene Copolymer

Tuesday, November 5, 2019

General Information

Product Description

Fusabond® M623XF resin is a random ethylene copolymer, incorporating a monomer which is classified as being a maleic anhydride equivalent for application uses.

The exact composition is considered to be proprietary information.

Applications:
Fusabond® M623XF is used as a modifier to be included in hot melt formulations for enhancing the performance of hot melt adhesives. It is miscible with EVA and Ethylene acrylic ester copolymers:

- It is best used when incorporated in hot melt formulations of EVA or Ethylene acrylic ester copolymers for enhancing and expanding adhesion performance.
- Because of its high fluidity and higher melting point, it may also impart processing and handling benefits for hot melt formulations.

Fusabond® M623XF can also be dispersed in latex form, or ground into powder form, for other process applications, and end uses.

Applications include but are not limited to:

- Adhesives, Polymer Modification, Coupling agent, Powder coating

General			
Material Status	• Experimental: Active		
Availability	• Africa & Middle East • Asia Pacific	• Europe • Latin America	• North America
Uses	• Adhesives	• Blending	• Coating Applications
Forms	• Pellets		

ASTM & ISO Properties [1]

Physical	Nominal Value	Unit	Test Method
Density / Specific Gravity	0.942		ASTM D792
Density	0.940	g/cm³	ISO 1183
Melt Mass-Flow Rate			ASTM D1238
120°C/2.16 kg	60	g/10 min	
190°C/2.16 kg	400	g/10 min	
Melt Mass-Flow Rate (MFR)			ISO 1133
120°C/2.16 kg	60	g/10 min	
190°C/2.16 kg	400	g/10 min	
Thermal	**Nominal Value**	**Unit**	**Test Method**
Melting Temperature (DSC)			
--	212	°F	ISO 3146
--	212	°F	ASTM D3418
Freezing Point - DSC			
--	176	°F	ASTM D3418
--	176	°F	ISO 3146
Additional Information	**Nominal Value**	**Unit**	
Processing Temperature	< 455	°F	

Notes

[1] Typical properties: these are not to be construed as specifications.